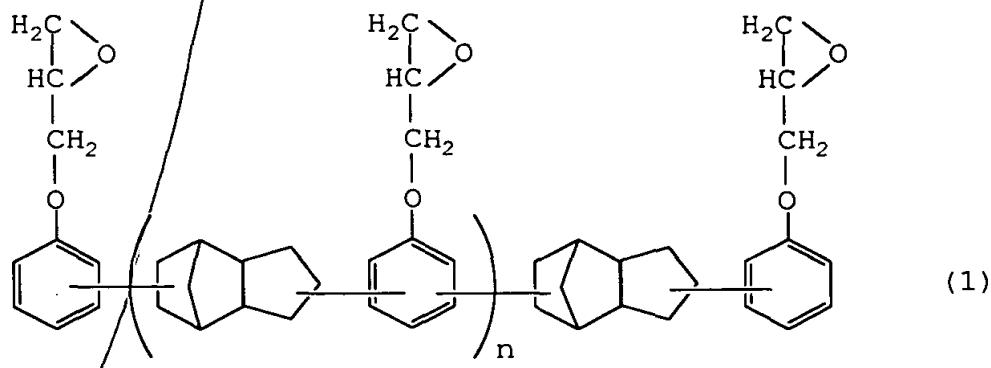


CLAIMS

1. A cyanate-epoxy resin composition comprising (A) a cyanate type compound containing two or more cyanto groups in one molecule thereof, (B) an epoxy resin, and (C) a curing accelerator as main components, wherein the epoxy resin is derived from a dicyclopentadiene-phenol polyaddition product having a dicyclopentadiene skeleton represented by the following formula (1), and the curing accelerator comprises (i) a compound having a catalytic function to accelerate the curing reaction of the cyanate type compound containing two or more cyanato groups in one molecule and (ii) a compound having a catalytic function to accelerate the curing reaction of the epoxy resin:



(wherein n is 0 or a positive integer).

2. A cyanate-epoxy resin composition according to Claim 1, wherein the compound having a catalytic function to accelerate the curing reaction of the cyanate type compound containing two or more cyanato

groups in one molecule is an organic metal salt or an organic metal complex, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin is an imidazole compound.

3. A cyanate-epoxy resin composition according to Claim 2, wherein the organic metal salt or the organic metal complex is an organic metal salt or an organic metal complex of iron, copper, zinc, cobalt, nickel, manganese or tin.

4. A cyanate-epoxy resin composition according to any one of Claims 1 to 3, wherein the epoxy resin (B) is contained in an amount of 50 to 250 parts by weight and the curing accelerator (C) in an amount of 0.1 to 5 parts by weight per 100 parts by weight of the cyanate type compound (A) containing two or more cyanato groups in one molecule.

5. A cyanate-epoxy resin composition according to any one of Claims 1 to 4, which further comprises an antioxidant (D).

6. A cyanate-epoxy resin composition according to Claim 5, wherein the antioxidant (D) is contained in an amount of 0.1 to 20 parts by weight per 100 parts by weight of the cyanate type compound (A) containing two or more cyanato groups in one molecule.

7. A prepreg obtained by impregnating a cyanate-epoxy resin composition described in any one of Claims 1 to 6 in a base, and drying the same.

8. A metal foil-laminated plate obtained by

laminating a metal foil on one side or both sides of the prepreg described in Claim 7 or a laminate thereof, and subjecting the laminate to hot-press molding.

9. A printed wiring board obtained by conducting a circuit-forming work on the metal foil of the metal foil-laminated plate described in Claim 8.

10. A cyanate-epoxy resin composition according to any one of Claims 1 to 6, wherein the compound having a catalytic function to accelerate the curing reaction of the cyanate type compound (A) is at least one of the organic metal salts or organic metal complexes of one or more of the metals selected from iron, copper, zinc, cobalt, nickel, manganese and tin, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin (B) is at least one compound selected from imidazole and its derivatives, organic phosphorus compounds, secondary amines, tertiary amines and quaternary ammonium salts.

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